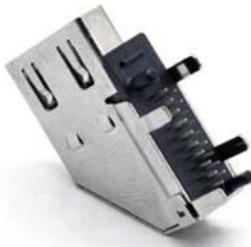


## 技术参数 / Technical parameter



HDMI-001C  
W23.10xD7.70xH16.40

PIN数(Number of contacts) : 19PIN

插座类型(Socket type) : HDMI

插座类别(Socket category): 母座/Mother seat

操作方式(Operation mode): 卧式/Horizontal

温度范围(Operating temp): -40°C TO +85°C

操作寿命(Operation life): 5,000 Cycles Min

额定负荷(Rated load): DC 40V 0.5A

焊接方式(Welding mode): 贴片式/SMT

接触电阻(Contact resistance):  $\leq 10\text{m}\Omega$ 

包装方式(Packaging method): 吸塑盘装/Tray

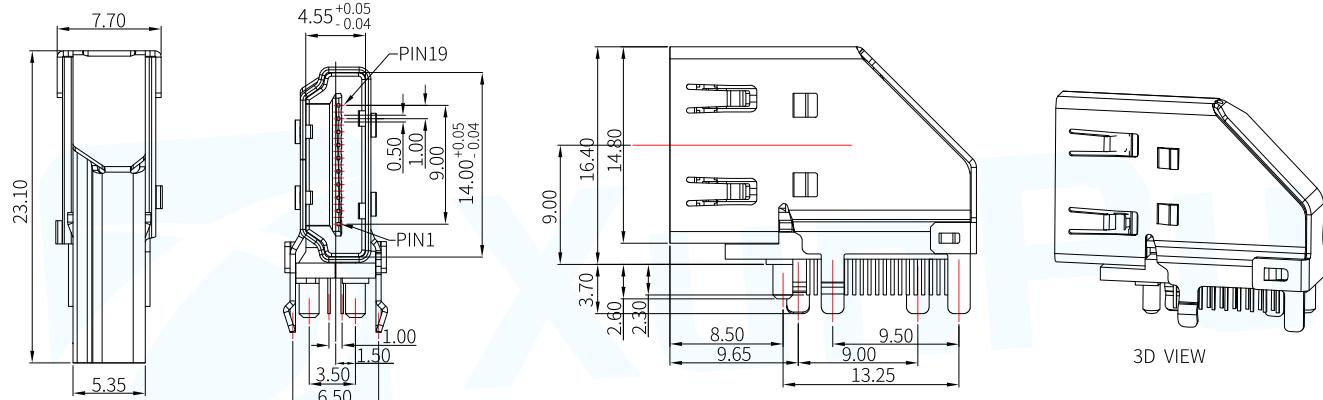
绝缘电阻(Insulation resistance):  $\geq 100\text{M}\Omega$ 

最小包装(Minimum packing): 100/PCS

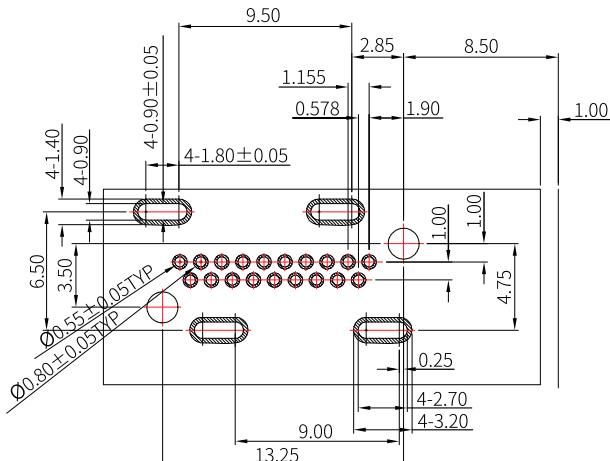
## 外形尺寸(UNIT:MM) / Size Chart

www.xunpuodianzi.com

更多资料请参考技术选型档!



## 线路板安装(UNIT:MM) / Mounting Dimensions



P.C.B LAYOUT(copper-side view)

## ● 引脚定义/Pin Definition

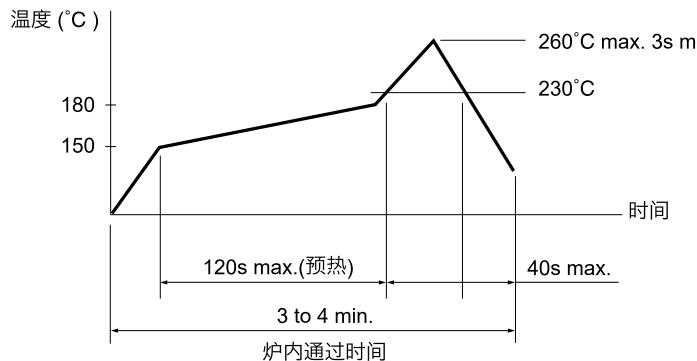
PIN	Signal Name	PIN	Signal Name
1	TMDS Data2+	11	TMDS Colck Shield
2	TMDS Data 2 Shield	12	TMDS Clock-
3	TMDS Data 2-	13	CEC
4	TMDS Data 1+	14	Reserved(N.C)
5	TMDS Data1 Shield	15	SCL
6	TMDS Data 1-	16	SDA
7	TMDS Data 0+	17	DDC/CEC Ground
8	TMDS Data0 Shield	18	+5V Power
9	TMDS Data 0-	19	Hot Plug Detect
10	TMDS Colck+		

# 焊接条件 / Welding conditions

## 回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products

温度分布/Temperature distribution



### 注:

1. 加热方式:以远红外线上下加热方式。
2. 温度测量:用Φ0.1~0.2的 CA(K)或 CC(T) 测量位置在焊接连接部(锡/铜箔面)。
3. 固定方式:采用耐热胶带。

## 手焊式/Hand welding

项目/Project	条件/condition
焊接温度 Welding temperature	350°C max.
持续焊接时间 Continuous welding time	3s max.
焊剂斗容量 Flux bucket capacity	60W max.

## 浸焊式/Immersion soldering

项目/Project	条件/condition
助焊剂附着量 Flux adhesion	不附着于零部件贴装面的程度 Not attached to the mounting surface of components
预热温度 Preheating temperature	印刷电路板焊接面的周围温度 100°C max. The temperature around the welding surface of PCB is 100 °C max
预热温度时间 Preheat temperature time	60s max.
焊接温度 welding temperature	260°C max.
焊接浸渍时间 Welding immersion time	5s max.
焊接次数 Welding times	2 times max.